

Date: September 2023
Rev: IV
No. of Components: Two
Mix Ratio by Weight: 100 : 8.5
Specific Gravity: Part A: 2.40 Part B: 0.99
Pot Life: 30 Minutes
Shelf Life- Bulk: One year at room temperature

Recommended Cure: 80°C / 2 Hours

Minimum Alternative Cure(s):

May not achieve performance properties listed below
 60°C / 4 Hours
 23°C / 2-3 Days

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: EPO-TEK® T7110-38 is a two component, thermally conductive, electrically insulating epoxy designed for heat sinking electronics and semiconductors. It is designed to be a higher viscosity and more thixotropic version of EPO-TEK® T7110.

Typical Properties: Cure condition: 80°C / 2 Hours Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	Part A: Grey	Part B: Clear/Colorless
* Consistency:	Smooth paste	
* Viscosity (23°C) @ 10 rpm:	12,000 - 27,000	cPs
Thixotropic Index:	3.5	
* Glass Transition Temp:	≥ 40	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	34	x 10 ⁻⁶ in/in°C
Above Tg:	116	x 10 ⁻⁶ in/in°C
Shore D Hardness:	88	
Die Shear @ 23°C:	18	Kg
Degradation Temp:	329	°C
Weight Loss:		
@ 200°C:	0.05	%
@ 250°C:	0.39	%
@ 300°C:	1.24	%
Suggested Operating Temperature:	< 250	°C (Intermittent)
Storage Modulus:	730,845	psi
* Particle Size:	≤ 50	microns

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	1.4 W/mK
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This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782

www.epotek.com

